

1 2 3 4

A

B

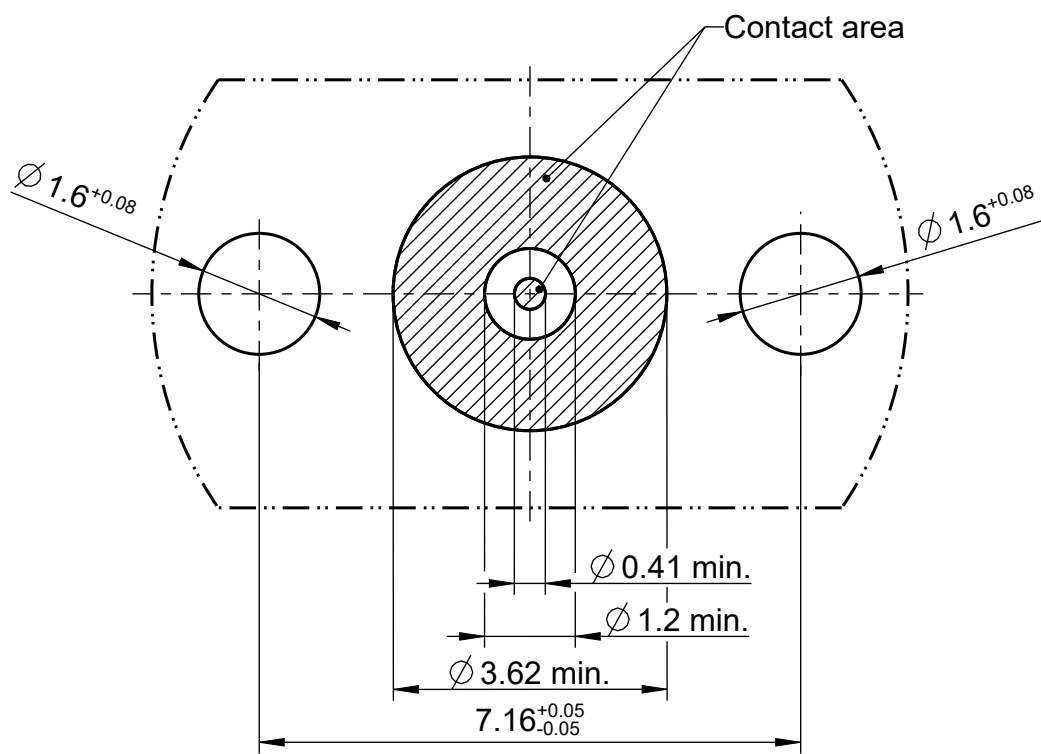
C

D

E

F

Leiterplatten-Layout  
 PCB layout  
 B 594C



*A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.*

Die angegebenen Maße und Toleranzen sind nur Empfehlungen.  
*The stated dimensions are only recommendations.*

<b>Rosenberger</b>			general tolerance		assembly instr.: ---		scale: 10:1 ( )		crimp insert: ---	
			ISO 2768		panel piercing: ---		series: ---		cable: ---	
vertraulich / confidential			mH		---		---		---	
			date		name		title: <b>Leiterplatten-Layout PCB layout</b>			
drawn		13.02.2017		M_Knoll		drawing-no.: <b>MB_594C</b>				
check.		17.01.2019		G_Schiele						sheet: <b>1</b>
appr.		17.01.2019		M_Moder		of: <b>1</b>				
a00	19-s025	S_Schmid	14.01.2019							remarks: MB_594
400	18-2035	M_Ruf	12.11.2018							
300	18-v404	M_Knoll	12.06.2018							
200	17-m565	N_Topcagic	28.07.2017							
100	16-e103	M_Knoll	05.04.2017							
rev. change-no		name		date						

1 2 3 4